

WHAT IS CLAIMED IS:

1. A wafer, comprising:
protein material, wherein said protein material comprises, by weight, between about 26% and about 99% of a wafer.

2. The wafer of claim 1, further comprising:
flavorings or seasonings;
oil; and
an emulsifier.

3. The wafer of claim 1, wherein said protein material is whey protein, wheat protein, soy protein, calcium caseinate, egg white protein or a combination thereof.

4. The wafer of claim 1, comprising:
caseinate; and
whey protein isolate;
wherein the ratio of caseinate to whey protein isolate is about 1:5.4 to about 1:5.7.

5. The wafer of claim 1, comprising:
whey protein isolate; and
soy protein isolate.

6. The wafer of claim 5, wherein the ratio of soy protein isolate to whey protein isolate ranges from about 1:1 to about 1:4.

7. A wafer, comprising by weight:
up to about 99% whey protein isolate;
up to about 99% soy protein isolate;
up to about 11% calcium caseinate; and
up to about 23% egg white protein.

8. The wafer of claim 7, wherein:
whey protein isolate comprises about 60%;
soy protein isolate comprises about 15%;
calcium caseinate comprises about 11%; and
egg white protein comprises about 8%.

9. The wafer of claim 7, further comprising up to about 99% by weight wheat protein.

10. A wafer, comprising:
at least one protein material; and
starch;
wherein said starch comprises up to about 65% of a wafer.

11. The wafer of claim 10, wherein said starch is pastry flour, Hi-maize flour or wheat flour.

12. The wafer of claim 10, wherein:
said at least one protein material comprises about 26% by weight of said wafer; and
said starch comprises about 64% by weight of said wafer.

13. The wafer of claim 10, wherein said protein material comprises:
whey protein isolate comprising about 11% by weight of said wafer;
soy protein isolate comprising about 11% by weight of said wafer;
calcium caseinate comprising about 2% by weight of said wafer; and
egg white proteins comprising about 2% by weight of said wafer.

14. The wafer of claim 13, further comprising wheat proteins.

15. A base wafer batter, comprising:
protein material; and
water;

wherein said protein material comprises up to about 65% of a base wafer batter; and
wherein said water comprises up to about 60% of said base wafer batter.

16. The base wafer batter of claim 15, wherein the ratio of said protein material to said water ranges from about 1:1.5 to about 1:2.

17. A base wafer batter, comprising:
protein material;
starch; and
water;

wherein said protein material comprises up to about 65% of said base wafer batter;
said starch comprises up to about 30% of said base wafer batter; and
said water comprises up to about 60% of said base wafer batter.

18. The base wafer batter of claim 17, wherein:
said protein material comprises about 12% by weight of said batter;
said starch comprises about 30% by weight of said batter; and
said water comprises about 54% by weight of said batter.

19. A snack food, comprising a protein enhanced wafer, wherein said wafer comprises up to about 99% protein.

20. The snack food of claim 19, further comprising:
a cream filling;
chocolate;
an icing; or
a combination thereof.

21. A method for making a wafer, comprising:
making a base wafer batter; and
baking said batter;
wherein said batter comprises up to about 65% protein, and wherein whey protein is added to said batter before soy protein is added to said batter.

22. The method of claim 21, wherein said batter bakes at a temperature from about 140°C to about 165°C and for a time period from about 1.5 minutes to about 2.5 minutes.

23. A method for making a base wafer batter, comprising:
first making a solution of water, egg whites and emulsifiers; and
then combining proteins, wherein whey protein is added and mixed before soy protein is added and mixed.

24. The method of claim 23, further comprising adding and mixing wheat protein after whey protein is added and mixed and before soy protein is added and mixed.

25. The method of claim 23, wherein caseinate is added and mixed before whey protein is added and mixed.

26. The method of claim 23, further comprising adding and mixing salt, seasonings, flavorings, or a combination thereof.

27. A method for making a base wafer batter, comprising:
making a protein slurry;
making a starch slurry; and
mixing together said protein slurry with said starch slurry.

28. The method of claim 27, wherein said protein slurry is made by:
first mixing together water and egg whites;
then adding oil and an emulsifier to the mixture and mixing;

then adding caseinate and mixing;
then adding protein and mixing, wherein whey protein is added and mixed before
soy protein is added and mixed; and
wherein said starch slurry is made by:
combining water, starch, an emulsifier, oil, salt and a leavening agent and mixing.

29. The method of claim 28, further comprising adding and mixing wheat protein
after whey protein is added and mixed and before soy protein is added and mixed.

30. A method for making a snack food, comprising:
making a protein enhanced, low carbohydrate wafer;
forming said wafer; and
coating, filling or dressing said wafer with a cream filling, icing or chocolate;
wherein said wafer is made by the method of claim 21.

31. A method for making a snack food, comprising:
making a protein enhanced, low carbohydrate wafer;
forming said wafer; and
coating, filling or dressing said wafer with a cream filling, icing or chocolate;
wherein said wafer is made by the method of claim 22.

32. A method for making a snack food, comprising:
making a protein enhanced, low carbohydrate wafer;
forming said wafer; and
coating, filling or dressing said wafer with a cream filling, icing or chocolate;
wherein said wafer is made by the method of claim 23.

33. A method for making a snack food, comprising:
making a protein enhanced, low carbohydrate wafer;
forming said wafer; and

coating, filling or dressing said wafer with a cream filling, icing or chocolate;
wherein said wafer is made by the method of claim 24.

34. A method for making a snack food, comprising:
making a protein enhanced, low carbohydrate wafer;
forming said wafer; and
coating, filling or dressing said wafer with a cream filling, icing or chocolate;
wherein said wafer is made by the method of claim 25.

35. A method for making a snack food, comprising:
making a protein enhanced, low carbohydrate wafer;
forming said wafer; and
coating, filling or dressing said wafer with a cream filling, icing or chocolate;
wherein said wafer is made by the method of claim 26.

36. A method for making a snack food, comprising:
making a protein enhanced, low carbohydrate wafer;
forming said wafer; and
coating, filling or dressing said wafer with a cream filling, icing or chocolate;
wherein said wafer is made by the method of claim 27.

37. A method for making a snack food, comprising:
making a protein enhanced, low carbohydrate wafer;
forming said wafer; and
coating, filling or dressing said wafer with a cream filling, icing or chocolate;
wherein said wafer is made by the method of claim 28.

38. A method for making a snack food, comprising:
making a protein enhanced, low carbohydrate wafer;
forming said wafer; and

coating, filling or dressing said wafer with a cream filling, icing or chocolate;
wherein said wafer is made by the method of claim 29.

39. A diet, comprising a snack food containing a protein enhanced, low carbohydrate wafer.

40. A wafer, comprising:
up to about 27 grams of protein per 28 grams of said wafer; and
up to about 4 grams of carbohydrates per 28 grams of said wafer.

41. A snack food comprising:
a wafer;
wherein said snack food comprises up to about 19 grams of protein per 28 grams of said snack food.

42. A snack food, comprising:
a wafer;
wherein said snack food comprises up to about 9 grams of carbohydrates per 28 grams of said snack food.